



# Product Change Notification

## 113742 - 00

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**contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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# Product Change Notification

**Change Notification #:** 113742 - 00  
**Change Title:** Intel® Server System R2312IP4LHPC  
PCN 113742-00, Product Design, Label  
Update the Power Distribution Board, Add a  
Rubber and a KCC Safety Label  
**Date of Publication:** March 24, 2015

## Key Characteristics of the Change:

Product Design, Label

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material *:</b>	Effective Immediately
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2312IP4LHPC:

1. Increase the two capacitor values of C11 and C13 on the Spare Power Distribution Board (PDB) FBP750PDB from 0.1 $\mu$ F to 2.2 $\mu$ F to extend the duration of the Over Current Protection (OCP) circuit from 0.6ms to 8.0ms. This change prevents the potential system shutdown event triggered by the violation of the 240VA regulation of the OCP circuit.

Please refer to the Technical Advisory TA-1056-01 for more information.

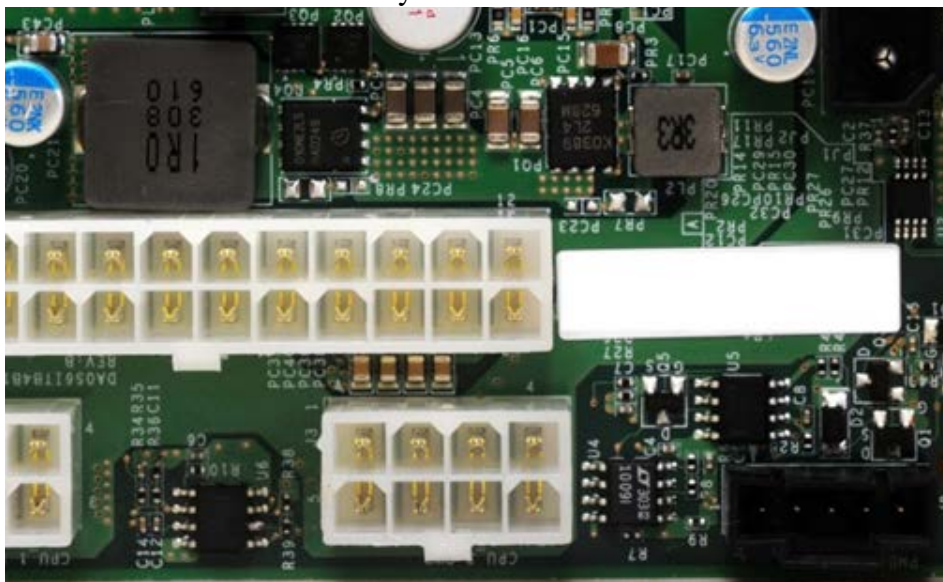


Figure-1: Location of Capacitors C11 and C13

2. Add a system integration rubber to better fix the air duct. Please see Figure-2.



Figure-2: System integration rubber

3. Add a new KCC safety label. See Figure-3a and Figure-3b for more details.



Figure-3a: Pre-Change (G35978-004)



Figure-3b: Post Change (G35978-005)

### Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the changes and determine the impact to their applications.

### Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2312IP4LHPC	916052	G62274-003	G62274-004

### Reference Documents / Attachments:

**Document:**

TA-1056-01

**Location #:**

<http://www.intel.com/support>

### PCN Revision History:

**Date of Revision:**

March 24, 2015

**Revision Number:**

00

**Reason:**

Originally Published PCN